



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD90N10S4-06		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001610782						
<b>Package</b>		PG-TO252-3-313		<b>Weight*</b>		319.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.426	1.38	1.38	13838	13838
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		460	
	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	copper	7440-50-8	147.096	45.98	46.04	459881	460479
wire	non noble metal	aluminium	7429-90-5	4.210	1.32	1.32	13164	13164
encapsulation	organic material	carbon black	1333-86-4	1.361	0.43		4256	
	plastics	epoxy resin	-	23.824	7.45		74485	
	inorganic material	silicondioxide	60676-86-0	110.954	34.69	42.57	346886	425627
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11693	11693
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4441	4452
solder	noble metal	silver	7440-22-4	0.086	0.03		268	
	non noble metal	tin	7440-31-5	0.069	0.02		214	
	non noble metal	lead	7439-92-1	3.272	1.02	1.07	10231	10713
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.00	6.01	59956	60034
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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